

WIRE BONDERS AND METHODS OF WIRE-BONDING

ABSTRACT OF THE DISCLOSURE

[0032] Wire bonders and methods of wire-bonding are disclosed herein. In one embodiment, a method includes attaching a wire to a terminal of a microelectronic component and generating an arc between a first electrode and a second electrode to sever the wire at a point at least proximate to the first and second electrodes. In another embodiment, a wire bonder includes a bond head having a capillary, a first electrode and a second electrode each disposed relative to the bond head, and a controller operably coupled to the first and second electrodes. The controller has a computer-readable medium containing instructions to perform the above-mentioned method. It is emphasized that this Abstract is provided to comply with the rules requiring an abstract. It is submitted with the understanding that it will not be used to interpret or limit the scope or meaning of the claims. 37 C.F.R. § 1.72(b).